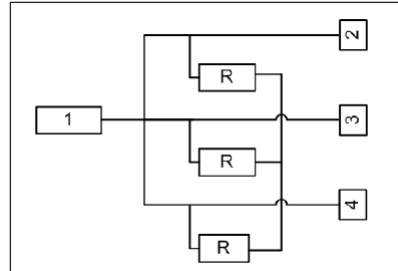


Features

- Frequency: 8-12GHz
- Insertion Loss: 0.3dB
- Input/Output: 50Ω matched
- Die Size: 1.75 x 1.2 x 0.1 mm

Functional Block Diagram

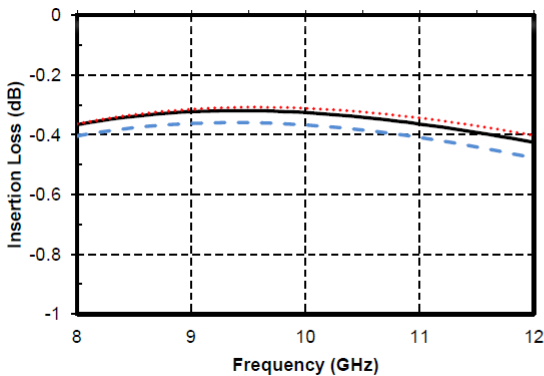


Electrical Specifications

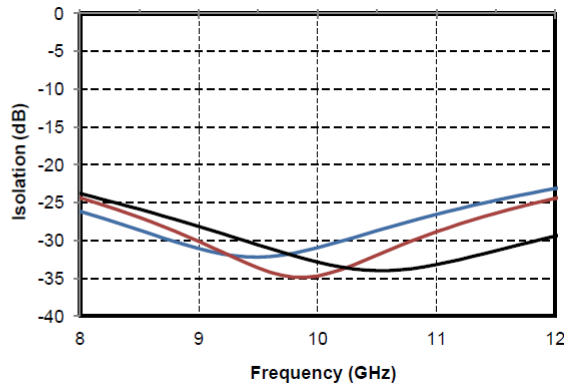
TA = +25°C

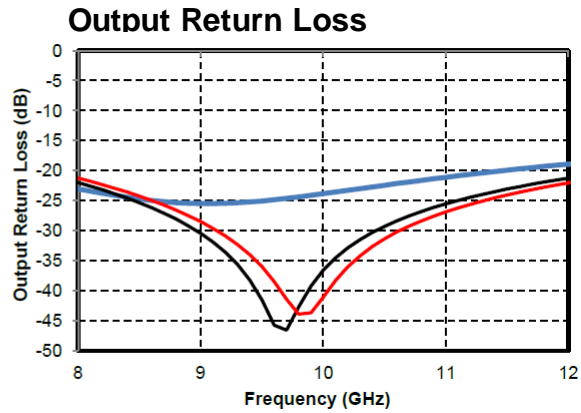
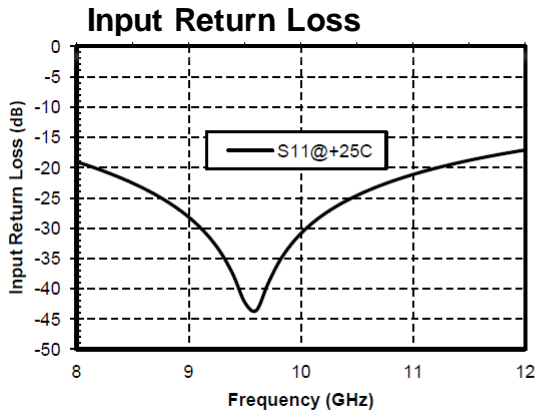
Parameters	Min.	Typ.	Max.	Units
Frequency	8-12			GHz
Insertion Loss	0.2	0.3	0.4	dB
Flatness		±0.1		dB
Isolation	23	29		dB
Input Return Loss	17	22		dB
Output Return Loss	21	25		dB

Insertion Loss



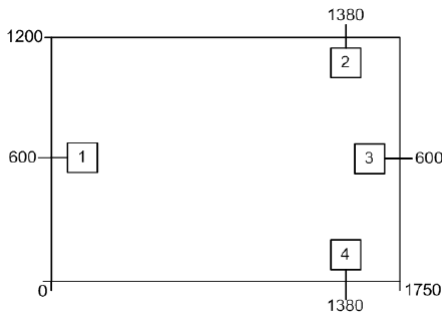
Isolation



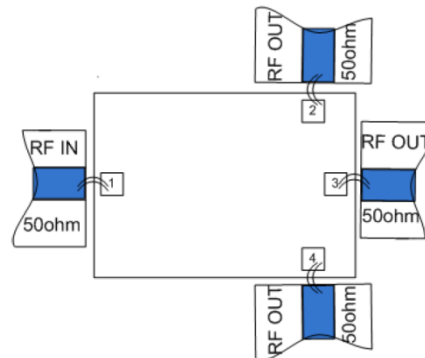


Outline Drawing

All Dimensions in um



Assembly Drawing



Pad Description

Pad	Function	Description
1	RF IN	RF Input Port
2,3,4	RF OUT	RF Output Port
Die bottom	GND	Die bottom must be connected to RF/DC ground.

Maximum Ratings:

1. Maximum input power: +40dBm
2. Operating temperature: -55°C to +85°C
3. Storage temperature: -65°C to +150°C